Course Code	ECE 516	
Course Name	System on Chip Design and Test	
Credits	System on Chip Design and Test	
Course Offered to	UG/PG	
Course Offered to	This course introduces students to design trends in deep submicron (DSM) e	ra including scaling trend clock cycle and
	power issues; Role of interconnects in contemporary SoC Design; System-or	
Course Description	design and reusability, Multiprocessor SoC platform design, 3D integration, of	
- Course Bosonphon	Pre-requisites	on-crip optical and wireless communication,
Pre-requisite (Mandatory)	·	Pre-requisite(other)
Introduction to VLSI Design, basic computer	rie-requisite (Desirable)	rie-requisite(otrier)
organization and architecture		
organization and aromicotare	Post Conditions	
CO1		CO3
Have knowledge and understanding of the		
design and technology trends, role of		
interconnects in contemporary SoC design,	Have knowledge of Design for testability (DFT), Test Access	3. Analyze, simulate and design complex
	Mechanism (TAM), concept of core-based test & IEEE P1500 standard for	
power distribution networks.		on low power and high-speed.
	Weekly Lecture Plan	
Week Number	•	Assignment/Labs/Tutorial
1	•	Reading Assignment 1
2	0	Reading Assignment 2
2	Delay in long wires and performance limitations, Interconnect coupling	Reading Assignment 2
	capacitance and its effect on wire delay, Crosstalk avoidance coding	
3,4		Reading Assignment 3, Quiz I
5	` '	Reading Assignment 4, Quiz II
5		<u> </u>
0		Reading Assignment 5, Quiz III
1	Fault modeling,	HW 1, Reading Assignment 6
8	Design for Testability (DFT)	Reading Assignment 7, Quiz IV
9	Test Access Mechanism (TAM)	Reading Assignment 8, Quiz V
10	Concept of core-based test & IEEE P1500 standard for SoC test	HW 2, Reading Assignment 9
	Design and Test of low-voltage CMOS circuits, Multiple Threshold CMOS	
l	(MTCMOS), Variable Threshold CMOS and other related methodologies for	
11	• ,	Reading Assignment 10, Quiz VI
12		Reading Assignment 11, Quiz VII
13	Future of SoCs: 3D integration, on-chip optical and wireless communication	Project Report & Poster
	Assessment Plan	
Type of Evaluation	Assessment Plan % Contribution in Grade	
Type of Evaluation Homework		
	% Contribution in Grade	
Homework	% Contribution in Grade	
Homework Quizzes	% Contribution in Grade 5 5	
Homework Quizzes Reading Assignment	% Contribution in Grade 5 5 15	
Homework Quizzes Reading Assignment Mid-Sem	% Contribution in Grade 5 5 15 20	
Homework Quizzes Reading Assignment Mid-Sem End-Sem	% Contribution in Grade 5 5 15 20 25 30	
Homework Quizzes Reading Assignment Mid-Sem End-Sem Project	% Contribution in Grade       5       5       15       20       25       30       Resource Material	
Homework Quizzes Reading Assignment Mid-Sem End-Sem	% Contribution in Grade  5 5 15 20 25 30 Resource Material	nology, Hodges, Jackson and Saleh, McGraw
Homework Quizzes Reading Assignment Mid-Sem End-Sem Project	% Contribution in Grade       5       5       15       20       25       30       Resource Material	nology, Hodges, Jackson and Saleh, McGraw-
Homework Quizzes Reading Assignment Mid-Sem End-Sem Project Type	% Contribution in Grade  5 5 15 20 25 30 Resource Material  Title Analysis and Design of Digital Integrated Circuits - In Deep Submicron Techn	
Homework Quizzes Reading Assignment Mid-Sem End-Sem Project Type	% Contribution in Grade  5 5 15 20 25 30 Resource Material  Title Analysis and Design of Digital Integrated Circuits - In Deep Submicron Technolit, Third Edition, 2004.	